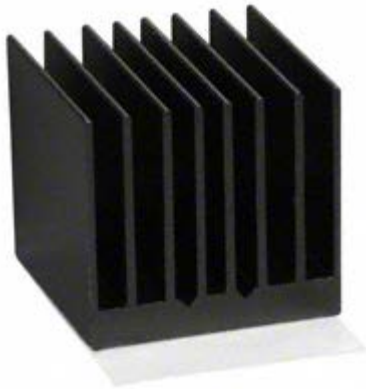


BGA Heat Sink - High Performance Straight Fin w/Thermal Tape



*Image above is for illustration purpose only.

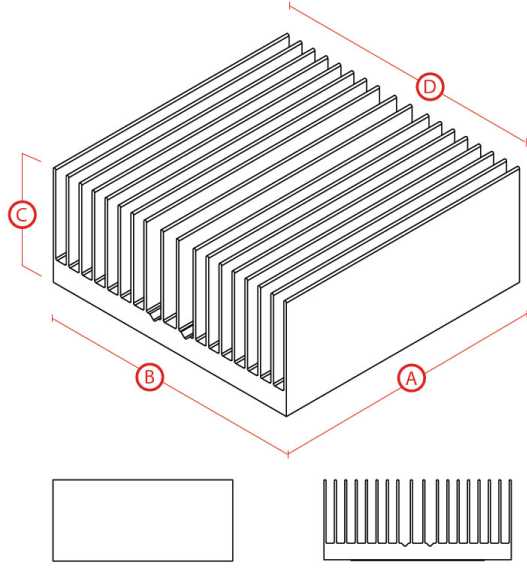
Features & Benefits

- High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- Designed specifically for BGAs and other surface mount packages
- Comes preassembled with high performance thermal interface material

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	4 °C/W	3.2 °C/W	2.8 °C/W	2.5 °C/W	2.3 °C/W	2.1 °C/W	2 °C/W
	Ducted Flow	2.6	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
	27.00 mm	27.00 mm	24.50 mm	N/A mm	T412	BLACK-ANODIZED
Notes: • Dimension A and B refer to component size. • Dimension C is the heat sink height from the bottom of the base to the top of the fin field. • ATS-54270W-C2-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint-Gobain C675). • Thermal performance data are provided for reference only. Actual performance may vary by application. • ATS reserves the right to update or change its products without notice to improve the design or performance. • ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant. • Contact ATS to learn about custom options available.						

*Image above is for illustration purpose only.

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

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